

<b>1. Electrical Performance</b>			
<b>Factor</b>	<b>Phase-Shifted Full-Bridge (PSFB)</b>	<b>Boost + Two-Switch Forward Converter</b>	<b>References</b>
<b>Input Voltage Range</b>	Wide (e.g., 350–450 V typical, can extend to 200–800 V for EV chargers)	Boost stage handles wide range (e.g., 85–265 VAC rectified to 120–400 V DC), Forward stage sees regulated bus	TI PSFB Guide [ti.com], IEEE EV Charging PSFB [ieeexplore.ieee.org] <a href="https://www.infineon.com/assets/row/public/documents/10/59/infineon-hv-dcdc-v2-whitepaper-en.pdf">https://www.infineon.com/assets/row/public/documents/10/59/infineon-hv-dcdc-v2-whitepaper-en.pdf</a>
<b>Output Voltage Range</b>	Regulated, typically 12–54 V for telecom/server; can scale to 250–1000 V for EV chargers	Forward stage provides regulated low voltage (e.g., 12–48 V) after boost. Transformer design becomes challenging.	Infineon PSFB Reference Design [infineon.com]
<b>Output Current Capability</b>	High current capability due to full-bridge and synchronous rectification	Moderate; forward stage limited by transformer reset and duty cycle	<a href="#">TI Seminar PSFB Fundamentals [ti.com]</a>
<b>Efficiency</b>	92–96% (ZVS reduces switching losses, more current paths, with less $R_{ds\ ON}$ , losses can be reduced)	85–91% (boost stage hard-switching dominates losses)(Hard switching loss can be scaled as $P_{sw} = K \cdot V \cdot I \cdot f_{sw}$ ) (cumulative losses increase)	Infineon PSFB Control [infineon.com], Infineon Boost Guide [infineon.com], <a href="https://www.princeton.edu/~minjie/files/chen-multidcdc-2017.pdf">https://www.princeton.edu/~minjie/files/chen-multidcdc-2017.pdf</a>
<b>Power Density</b>	High ( with SiC MOSFETs, can achieve higher power density) (up to 67 W/in <sup>3</sup> with GaN and 350 kHz switching)	Lower (two stages increase size; boost inductor adds bulk)	Infineon PSFB Reference Design [infineon.com]
<b>Voltage Ripple</b>	Low output ripple with proper LC filter; input ripple depends on bus capacitance	Boost stage introduces higher input ripple; forward stage output ripple moderate	ResearchGate PSFB Ripple Analysis [researchgate.net]
<b>Current Ripple</b>	Low on secondary due to output inductor; primary ripple depends on phase-shift	Boost stage has high input current ripple; forward stage smoother	<a href="#">Infineon Boost Guide [infineon.com]</a>
<b>Transient Response</b>	Fast (digital control + feed-forward improves line/load response)	Slower due to two-stage architecture	Infineon PSFB Reference Design [infineon.com]

<b>Regulation</b>	Excellent (line and load regulation with digital control and synchronous rectifiers)	Good but depends on coordination between boost and forward stages	<a href="#">TI PSFB Guide [ti.com]</a>
<b>Switching Frequency</b>	Typically 50–200 kHz (up to 350 kHz with GaN)	Boost: 50–100 kHz; Forward: 50–100 kHz	<a href="#">Infineon PSFB Reference Design [infineon.com]</a>
<b>Control Method</b>	Voltage mode or peak current mode; digital control common	Boost: voltage or current mode; Forward: voltage mode	TI PSFB Guide [ti.com], Infineon Boost Guide [infineon.com]

## 2. Component Stress

Factor	Phase-Shifted Full-Bridge (PSFB)	Boost + Two-Switch Forward Converter	References
<b>Switch Voltage Stress</b>	Each MOSFET sees $\approx$ <b>input bus voltage</b> (e.g., 400–750 V typical)	Boost switch sees <b>full input voltage</b> ; Forward switches see <b>output voltage</b>	TI PSFB Design Guide [ti.com], Infineon PSFB Reference Design [infineon.com], Infineon Boost Guide [infineon.com]
<b>Switch Current Stress</b>	Moderate, distributed across 4 MOSFETs; circulating current adds stress at light load	Boost switch carries <b>full input current</b> ; Forward switches carry <b>load current</b>	Infineon PSFB Control [infineon.com]
<b>Diode Voltage/Current Stress</b>	Secondary diodes see <b>output voltage</b> ; body diodes on MOSFETs see bus voltage	Boost diode sees <b>output voltage</b> ; Forward rectifiers see <b>output voltage and load current</b>	<a href="#">TI PSFB Fundamentals [ti.com]</a>
<b>Inductor Current Ripple</b>	Output inductor ripple depends on duty cycle and switching frequency; typically low due to synchronous rectification	Boost inductor ripple is significant (depends on CCM/DCM mode); Forward stage ripple moderate	TI PSFB Guide [ti.com], Infineon Boost Guide [infineon.com]
<b>Capacitor RMS Current</b>	Input capacitor handles high RMS current due to full-bridge switching; output capacitor ripple low	Boost stage input capacitor sees high RMS current; forward stage output capacitor handles moderate ripple	TI PSFB Guide [ti.com]
<b>Thermal Stress (Junction Temp, Heat Dissipation)</b>	Lower switching losses due to ZVS; conduction losses dominate; GaN/SiC improves thermal profile	Boost stage hard-switching increases thermal stress; forward stage moderate	ResearchGate PSFB Thermal Analysis [researchgate.net], Infineon PSFB Simulation Tool [plex.infineon.com]

## 3. Topology Characteristics

Factor	Phase-Shifted Full-Bridge (PSFB)	Boost + Two-Switch Forward Converter	References
Isolation	<b>Isolated</b> (uses transformer for galvanic isolation)	Boost stage: <b>Non-isolated</b> , Forward stage: <b>Isolated</b>	TI PSFB Guide [ti.com], Infineon PSFB Reference Design [infineon.com]
Number of Active Switches	4 MOSFETs in full bridge	Boost: 1 MOSFET, Forward: 2 MOSFETs → Total = 3	TI PSFB Fundamentals [ti.com], Infineon Boost Guide [infineon.com]
Number of Passive Components	Transformer + output inductor + filter capacitors	Boost inductor + transformer + output filter capacitors	<a href="#">TI PSFB Guide [ti.com]</a>
Complexity of Design	High (phase-shift modulation, ZVS timing, synchronous rectification)	Moderate (two separate control loops: boost + forward)	Infineon PSFB Control [ti.com]
Size and Weight	Compact for high power (high power density up to 67 W/in <sup>3</sup> with GaN)	Larger (two stages increase size; boost inductor adds weight)	Infineon PSFB Reference Design [infineon.com]
Scalability (Higher Power)	Excellent (used in 10 kW–50 kW EV chargers and industrial supplies)	Limited (boost stage becomes inefficient at very high power)	ResearchGate PSFB High-Power Design [researchgate.net]

#### 4. Loss Analysis

Loss Component	Phase-Shifted Full-Bridge (PSFB)	Boost + Two-Switch Forward Converter	References
<b>Conduction Losses (Switches, Diodes, Inductors)</b>	Moderate; distributed across 4 MOSFETs and synchronous rectifiers; circulating current adds extra loss at light load	Higher in boost stage due to single switch carrying full input current; forward stage moderate	TI PSFB Fundamentals [ti.com], Infineon PSFB Control [infineon.com], Infineon Boost Guide [infineon.com]
<b>Switching Losses</b>	Very low due to ZVS on primary switches; lagging leg may lose ZVS at light load	High in boost stage (hard-switching at high voltage); forward stage moderate	TI PSFB Design Guide [ti.com], Infineon Switching Loss Guideline [infineon.com]
<b>Core Losses (Magnetic Components)</b>	Lower due to high-frequency operation and optimized transformer design; but leakage inductance adds circulating current	Boost inductor core losses significant at high ripple; forward transformer moderate	<a href="#">ResearchGate HF Conductor Losses [researchgate.net]</a>
<b>Gate Drive Losses</b>	Higher (4 MOSFETs + synchronous rectifiers); mitigated by efficient drivers	Lower overall (3 main switches), but two stages require separate drivers	<a href="#">TI PSFB Application Note [ti.com]</a>

<b>Auxiliary Losses (Control Circuitry)</b>	Higher due to complex phase-shift control and ZVS timing	Moderate; two controllers (boost + forward) but simpler algorithms	Infineon PSFB Control Strategies [infineon.com]
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## 5. Control & Dynamics

Factor	Phase-Shifted Full-Bridge (PSFB)	Boost + Two-Switch Forward Converter	References
<b>Control Complexity (Analog vs Digital)</b>	High: Often implemented with <b>digital controllers</b> for phase-shift timing, ZVS optimization, and synchronous rectification; analog possible but complex	Moderate: Two separate loops (boost + forward), usually analog or hybrid digital	TI PSFB Guide [ti.com], Infineon PSFB Control Strategies [infoscience.epfl.ch]
<b>Stability (Small-Signal Model, Loop Compensation)</b>	Requires detailed small-signal modeling for phase-shift modulation; digital control simplifies compensation	Boost and forward stages each need separate compensation; simpler than PSFB but more tuning effort overall	<a href="#">TI Seminar PSFB Fundamentals [studylib.net]</a>
<b>Dynamic Response (Speed of Regulation)</b>	Fast: Digital control with feed-forward improves transient response significantly	Slower: Two-stage architecture introduces delay; coordination between stages needed	Infineon PSFB Reference Design
<b>Soft Start Capability</b>	Built-in in most digital controllers; prevents inrush and overshoot	Common in analog controllers; implemented separately for boost and forward stages	<a href="#">TI PSFB Guide [ti.com]</a>
<b>Protection Features (OVP, UVP, OCP, OTP)</b>	Comprehensive: Digital control enables programmable OVP, UVP, OCP, OTP, and fault logging	Available but simpler; usually analog comparators for OVP/OCP, thermal shutdown in drivers	Infineon PSFB Control Strategies [infoscience.epfl.ch]

## 6. EMI & Noise

Aspect	PSFB (Phase-Shifted Full-Bridge)	Boost + Two-Switch Forward	References
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<b>EMI tendency (general)</b>	Typically <b>lower conducted/radiated EMI</b> than hard-switched bridges because PSFB achieves <b>ZVS</b> on the primary; reduced <b>dv/dt</b> and <b>di/dt</b> lowers high-frequency energy. At <b>light load</b> , ZVS may be lost on the lagging leg, increasing spikes.	<b>Higher EMI</b> , mainly from the <b>boost stage</b> (hard-switching at high bus voltage) and from diode reverse recovery/inductor ripple. Bridgeless/advanced PFC variants can further <b>increase CM emissions</b> if not carefully designed.	TI PSDS PSFB fundamentals (ZVS, EMI) PDF; TI power-tip on ZVS bridges PDF; TI E2E note on PSFB losing ZVS at light load Forum; TI bridgeless PFC EMI note AAJ article
<b>Dominant DM noise sources</b>	<b>Primary switch nodes</b> and <b>rectifier commutation</b> ; residual ringing from transformer leakage + MOSFET <b>Coss</b> ; output inductor ripple coupling to line via input bus.	<b>Boost inductor current ripple</b> (pulsating), <b>switch node</b> of the boost FET, and <b>diode</b> (or SR) recovery dominate DM noise; forward stage adds switching edges but at lower bus voltage.	TI “EMI tips & tricks” (DM mechanisms, $\pi$ filter) Slides; Infineon CCM boost design guide (loss/EMI design) PDF
<b>Dominant CM noise sources</b>	<b>Parasitic capacitance</b> from primary switch node/transformer to chassis; even with ZVS, high-frequency voltage swings couple CM currents to earth; transformer stray capacitance and layout are key.	<b>Parasitic capacitance</b> of boost switch node (large dv/dt relative to earth) and input wiring to chassis; bridgeless topologies often show <b>higher CM</b> due to floating return paths.	TI “EMI tips & tricks” (CM fundamentals and test setups) Slides; TI bridgeless PFC design discussion AAJ article
<b>Filtering requirements (typical)</b>	<b>Input DM:</b> $\pi$ filter (L-C-L/C), damping (R-C) to control peaking; <b>CM:</b> common-mode choke, Y-capacitors sized to limits.  Benefits from ZVS: <b>smaller</b> DM filter than hard-switched bridges; still need CM choke/Y-caps because transformer/wiring capacitance dominates CM.	<b>Stronger DM filtering</b> at input (larger <b>boost inductor ripple</b> ), often <b>two-stage <math>\pi</math> filter</b> ; <b>CM choke</b> frequently larger (especially bridgeless PFC) and careful <b>Y-cap placement</b> ; forward stage adds secondary-side snubbing/RC damping.	TI “EMI tips & tricks” ( $\pi$ filter design, parasitics, 2-stage filters) Slides; Infineon CCM boost guide & PFC controller docs (filter examples, protections) PDF

<b>Layout sensitivity</b>	High-side/low-side gate-drive loops must be compact; minimize <b>leakage</b> and <b>Cross-induced ringing</b> ; symmetry in transformer and short return paths reduce CM.	Minimize boost <b>switch-diode loop</b> area; tight <b>input loop</b> to cut DM; careful <b>earth/chassis coupling</b> to manage CM; bridgeless needs special sensing and <b>EMI mitigation</b> .	TI SMPS layout guide (dv/dt/di/dt, EMI) Slides; TI bridgeless PFC EMI note AAJ article
<b>Measured examples (indicative)</b>	PSFB reference designs show <b>high efficiency</b> and good EMI with proper filters and layout (e.g., 1–1.4 kW boards; GaN/Si devices, digital control).	High-efficiency PFC demo boards need <b>explicit EMI filters</b> (CM choke, DM $\pi$ filters); EMI section documented in dual-boost 3 kW demo notes.	Infineon PSFB reference designs (performance, control) PDFs; Infineon 3 kW dual-boost PFC demo (EMI filter section) PDF

## 7. Reliability & Robustness

<b>Fault Tolerance</b>	Moderate: Complex topology means more failure points; digital control can implement advanced fault handling (UVP, OVP, OCP, OTP, short-circuit protection)	Moderate: Two-stage design adds coordination complexity; simpler analog protection circuits common	TI PSFB Guide [research.tudelft.nl], Infineon PSFB Control Strategies [vicorpower.com]
<b>Component Count (affects MTBF)</b>	Higher: 4 MOSFETs + synchronous rectifiers + complex driver circuits; more components can reduce MTBF	Lower: Boost stage (1 MOSFET) + Forward stage (2 MOSFETs) + simpler drivers; fewer components generally improve MTBF	<a href="#">TI PSFB Fundamentals [researchgate.net]</a>
<b>Thermal Management</b>	Easier: ZVS reduces switching losses; conduction losses dominate; heat spread across multiple MOSFETs; GaN/SiC improves thermal profile	Harder: Boost stage hard-switching at high voltage $\rightarrow$ higher heat concentration; forward stage moderate	Infineon PSFB Reference Design
<b>Surge and Transient Handling</b>	Good: Transformer isolation provides inherent surge protection; digital control adds programmable transient response	Moderate: Boost stage exposed to line surges; forward stage isolated but coordination needed for surge handling	<a href="#">TI PSFB Guide [research.tudelft.nl]</a> , <a href="#">Infineon Boost Guide</a>

## 8. Practical Considerations

Factor	Phase-Shifted Full-Bridge (PSFB)	Boost + Two-Switch Forward Converter	References
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<b>Cost (Component &amp; Manufacturing)</b>	Higher: Requires 4 MOSFETs, synchronous rectifiers, complex magnetics, and digital controller; GaN/SiC devices increase cost but improve efficiency	Lower: Fewer active switches (3 total), simpler magnetics, and analog control possible; cost-effective for medium power	TI PSFB Fundamentals [ti.com], Infineon PSFB Reference Design [infineon.com]
<b>Availability of Components</b>	High: Widely supported by TI, Infineon, and others; GaN/SiC MOSFETs and digital controllers available for high-performance designs	High: Boost and forward converters use standard MOSFETs, diodes, and controllers; widely available for industrial and consumer designs	Infineon PSFB Control Strategies [infineon.com], Infineon Boost Guide [infineon.com]
<b>Ease of Implementation</b>	Complex: Requires precise phase-shift timing, ZVS optimization, and synchronous rectifier control; usually digital	Easier: Two separate control loops (boost + forward), analog or hybrid digital; simpler gate drive	<a href="#">TI PSFB Design Guide [ti.com]</a>
<b>PCB Area</b>	Larger: Full-bridge layout, transformer, and heat sinks; high-density designs possible with GaN and advanced cooling	Smaller: Boost inductor and forward transformer dominate; simpler layout overall	<a href="#">Infineon PSFB Evaluation Board [infineon.com]</a>
<b>Cooling Requirements</b>	Moderate: ZVS reduces switching losses; heat spread across multiple MOSFETs; advanced cooling concepts available	Higher: Boost stage hard-switching at high voltage → concentrated heat; forward stage moderate	<a href="#">Infineon PSFB Reference Design [infineon.com]</a>
<b>Maintenance</b>	More complex: Higher component count and digital control require skilled maintenance; firmware updates possible	Easier: Fewer components, simpler analog control; less specialized maintenance	ResearchGate PSFB Reliability Study [researchgate.net]

<b>9. Application-Specific Factors</b>			
<b>Factor</b>	<b>Phase-Shifted Full-Bridge (PSFB)</b>	<b>Boost → Two-Switch Forward</b>	<b>References</b>

<p><b>Bidirectional Capability</b></p>	<p><b>Feasible and proven</b> with appropriate modulation (e.g., bidirectional PSFB/B-PSFB). Achieves <b>near-full ZVS</b> in both directions and mitigates secondary overshoot when properly controlled; demonstrated <b>2 kW–3.3 kW</b> prototypes with <b>97.5–98% peak efficiency</b> in both buck and boost modes.</p>	<p>Typically <b>unidirectional</b> in common implementations. Making the <b>boost + forward</b> chain bidirectional is uncommon and <b>complex</b>, because the boost front end is <b>current-sourced</b> and the forward stage rectification must be replaced by an active bridge (raising device count and control complexity).</p>	<p>Bidirectional PSFB modulation &amp; prototypes (IEEE/ResearchGate) link [infineon.com]; Infineon/UGR bidirectional PSFB paper PDF [infineon.com]</p>
<p><b>Modularity</b></p>	<p>Commonly used as a <b>modular isolated DC-DC stage</b> in multi-kilowatt supplies (server PSUs, EV chargers), with standardized controllers and gate drivers; <b>fixed-frequency PSFB</b> integrates well with upstream PFC or DC bus and downstream PoL converters.</p>	<p>Also modular in two-stage supplies (PFC <b>boost</b> front end + isolated <b>forward</b> second stage). Easy to partition by power level, but <b>filtering/EMI</b> for the boost stage often dominates module interfaces.</p>	<p>TI PSFB fundamentals &amp; design seminar PDF [infineon.com]; Infineon 1 kW PSFB GaN reference design (modular digital controller &amp; telemetry) PDF [infineon.com]; PFC/boost stage modular resources PDF [ti.com]</p>
<p><b>Safety Standards Compliance</b></p>	<p>PSFB reference designs and controllers commonly target <b>IEC/UL</b> and <b>IT/server PSU</b> standards; isolation transformer facilitates meeting <b>SELV</b> and creepage/clearance. Digital PSFB platforms include <b>OVP/UVP/OCP/OTP</b> and <b>fault logging</b> to assist compliance and validation.</p>	<p>Boost PFC guidelines explicitly reference <b>IEC 1000-3-2 / EN 61000-3-2</b> harmonic/current limits; <b>EMI filters</b> sized to CISPR requirements. Isolation and SELV compliance achieved in the <b>forward stage</b>; protections typically analog (OVP/OCP, UVLO, thermal).</p>	<p>Infineon PSFB eval &amp; ref designs with protection &amp; PMBus (compliance-oriented features) PDF [studylib.net]; TI PSFB guide (controllers &amp; protections) PDF [infineon.com]; Infineon CCM boost PFC design guide (IEC/CISPR context) PDF [ieeexplore.ieee.org]; TI AAJ on bridgeless PFC EMI &amp; compliance PDF [research.tudelft.nl]</p>

<p><b>Environmental Conditions (Temperature, Humidity)</b></p>	<p>PSFB designs routinely validated for <b>wide ambient ranges</b> (e.g., -10 °C to 80 °C) and include <b>thermal modeling</b>; ZVS <b>reduces thermal stress</b>, easing operation at higher ambient and facilitating <b>higher power density</b> with appropriate heatsinks. Isolation helps when operating in <b>high-humidity</b> or noisy environments by breaking ground loops.</p>	<p>Boost stage's <b>hard-switching</b> increases switching losses and <b>hot-spots</b>; environmental robustness depends heavily on <b>thermal design</b> and <b>EMI filter durability</b>. Forward stage isolation helps with environmental noise; overall two-stage solutions see <b>larger passive components</b> that may be sensitive to humidity/contamination unless conformally coated.</p>	<p>Infineon PSFB WebSIM/PLECS tool (thermal overview; ambient &amp; heatsink parameters) Web [ieeexplore.ieee.org]; Infineon PSFB eval board with innovative cooling (97% peak efficiency) PDF [studylib.net]; Infineon dual-boost 3 kW PFC demo (EMI filter section &amp; thermal considerations) PDF [ti.com]</p>
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